



## PCB PROTECTION TAPES

WAVE SOLDER MASKING  
/MANUFACTURING

### PPI 701 0.025mm

- Polyimide film/silicone adhesive

### PPI 702 0.025mm 0.050mm

- Thicker adhesive version of PPI 701. Superior adhesion to uneven surfaces

### RD-042D 0.025mm 0.050mm

- Anti-static version

### RD-624B

- Anti-static Polyimide/  
conductive acrylic adhesive

### SP-255

- Crepe paper/silicone adhesive

### RD-487G

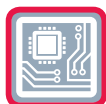
- Reinforced paper/PET laminate
- Silicone adhesive
- Suitable for HAL masking (hot air levelling)

### SP-479

- Version of PPI 255 with thicker adhesive layer
- Good adhesion to irregular board surfaces
- Supplied die-cut and with scored liner

### RD-673B

- Based on a grey flat backed paper coated with a totally black opaque rubber/resin
- This tape is applied to the lacquered PCB copper coated substrates and protects the photo-resistant from UV light exposure



## PPI 701

### self-adhesive masking tape

#### Application:

- high temperature-resistant masking tape for gold contacts on printed circuit boards during the wave soldering process

## PPI 702

### polyimide electrical tape with thermosetting silicone adhesive/Heat class H

high temperature resistant polyimide tape coated with a polysiloxane adhesive

#### Application:

- insulation tape for very high temperatures
- short term heat resistance up to 400°C

## RD-042D

### anti-static printed circuit board and conformal coating masking tape

based on polyimide film coated with a special surface conductive adhesive. Static generation during unwind and application is eliminated.

RD-042D can withstand wave soldering temperatures up to 300°C and leaves no adhesive residue on printed circuit boards during removal.

## RD-624B

### anti-static printed circuit board and conformal coating masking tape

based on polyimide film coated with a special surface conductive acrylic adhesive.

Static generation during unwind and application is eliminated. RD-624 can withstand wavesoldering temperatures up to 300°C and leaves no adhesive residue on printed circuit boards during removal.

## SP-255

## SP-479

### self-adhesive masking tape for hot air levelling and high temperature soldering processes

SP-255/SP-479 is a self-adhesive masking tape especially suitable for the protection of various areas of P.C. Boards (such as gold contacts) during high temperature flow solder processes. It is particularly recommended for masking edge connectors or fingers during hot air levelling.

#### Advantage:

- SP-255/SP-479 can be removed from printed circuit boards after the soldering operation without any danger of adhesive residue.

#### Note:

- When using SP-255/SP-479 as a mask in hot air levelling, the tape should be pressed onto the P.C.B. after application by means of rollers, preferable heated up to 100°C(212°F)

## RD-487G

### masking tape for hot air levelling processes

based on paper/polyester film coated with a heat resistant polysiloxane adhesive

RD-487D resists temperature up to 300°C short term and can be removed from the substrate without leaving any adhesive residue. The polyester reinforcement prevents tape tearing during removal.

#### Application:

- removable masking tape for hot air levelling processes
- suitable for masking of gold fingers
- RD-487D conforms to PCB irregularities and gives a fine masking line.
- It is recommended that after application of RD-487D, pressure rollers be used to provide intimate contact between tape and PCB.

## RD-673B

### low tack paper tape

based on a flatback impregnated paper coated with a low tack, black opaque rubber adhesive. The tape can be applied and removed from a wide range of surfaces without adhesive transfer. The adhesive is coated from aliphatic and aromatic solvents only.

#### Application:

- protection tape for pre-lacquered printed circuit board substrates